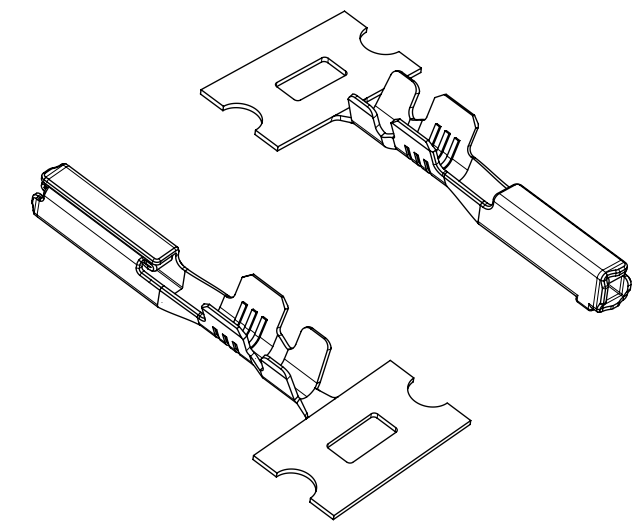
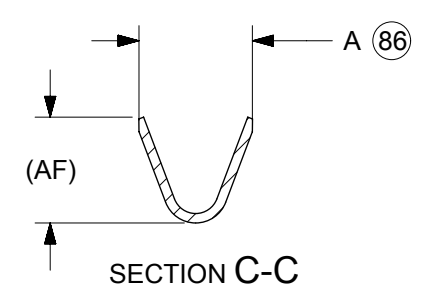
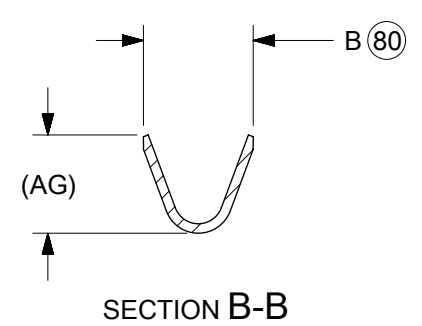
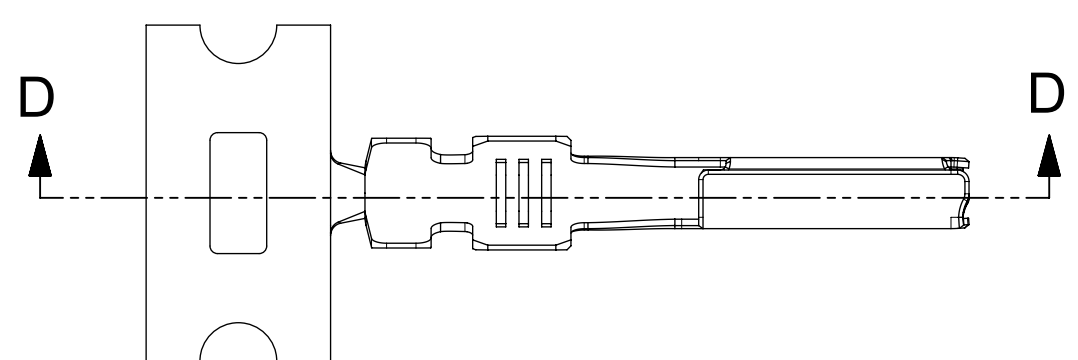


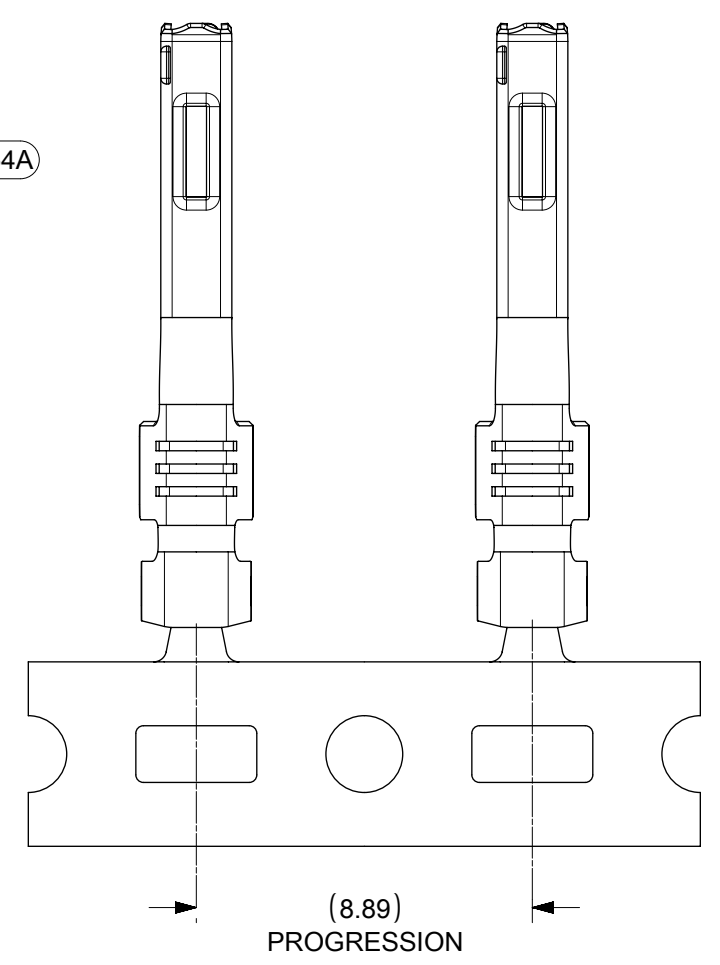
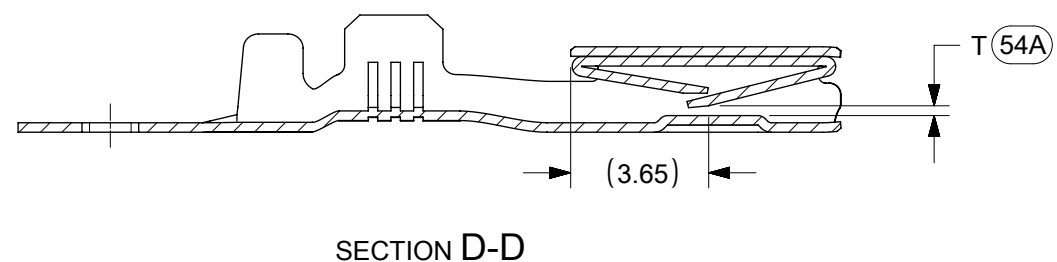
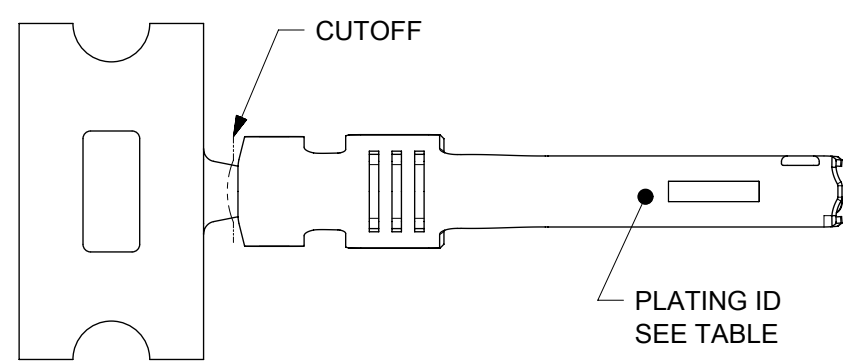
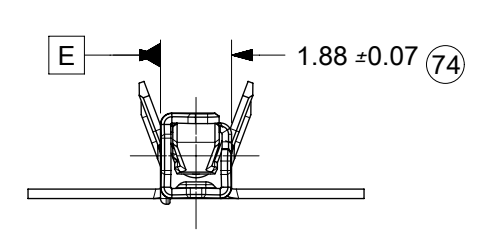
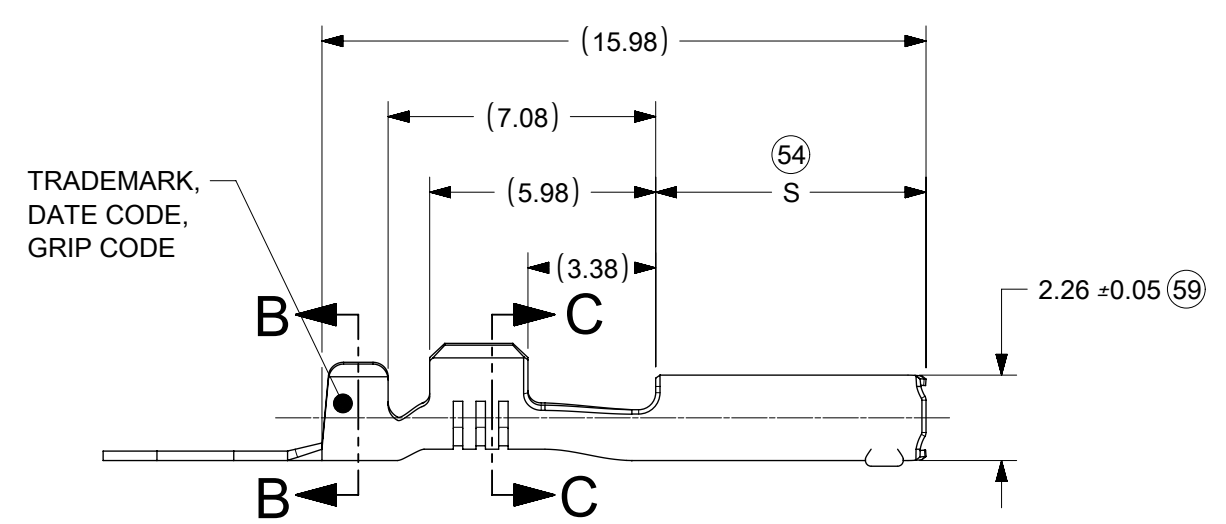


THE DATASHEET OF
0334670004+





ISO VIEWS
SCALE 3:1



- NOTES: (UNLESS OTHERWISE SPECIFIED)
- MATERIALS: SEE TABLE
 - PACKAGING SPECIFICATION: PK-31300-516 AND PK-30907-759
 - CRIMPING PER APPLICATION SPECIFICATION AS-33468-001
 - CRIMPED LEAD MEETS THE FOLLOWING:
 - SAE/USCAR-21, MAY 2002
 - SAE/USCAR-2, REV. 3, APRIL 2001
 - SAE/USCAR-12, REV. 2
 - GMW #3191 AUGUST 22, 2000 (DRAFT) TEMPERATURE CLASS 3, APPLIES ONLY TO Au PARTS
 - GMW #3191 JANUARY, 2005 TEMPERATURE CLASS 3, APPLIES ONLY TO Ag PARTS
 - PLATING NOTES:
 - TIN PLATING (ENTIRE TERMINAL)
 - ELECTRO REFLOW 1.90 - 3.30 MICROMETERS TIN OVER 0.25 - 0.76 MICROMETERS NICKEL
 - GOLD PLATING
 - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - ELECTRODEPOSITED GOLD 0.76 - 1.5 MICROMETERS IN CONTACT AREAS
 - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA
 - SILVER PLATING
 - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - ELECTRODEPOSITED PURE SILVER 99.5% PURITY SEMI-BRIGHT FINISH WITH NO BRIGHTENERS OR CHROMATES 1.9 - 3.3 MICROMETERS IN CONTACT AREAS
 - ANTI-TARNISH TREATMENT FOR SILVER PLATED AREA: SYNTHETIC HYDROCARBON CONTACT SURFACE FINISH OR EQUIVALENT
 - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA

WIRE SIZE	GRIP CODE	PART NUMBER	REEL PAYOFF DIRECTION	DIM A	DIM B	DIM S	DIM T	DIM AF	DIM AG	BASE MATERIAL	PLATING ID
22 AWG	A	33468-0002	D	2.3	2.3	7.15 ±0.10	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Sn Lead Free
		33468-0001	B	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Au Lead Free
		33467-0004	D	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-1001	D	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-2001	B	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
18/20 AWG	B	33468-0004	D	3.0	2.9	7.15 ±0.10	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Sn Lead Free
		33468-0003	B	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Au Lead Free
		33467-0006	D	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		33467-0005	B	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		34736-1002	D	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
34736-2002	B	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free		

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS mm	SCALE 5:1	CURRENT REV DESC:	molex			
GENERAL TOLERANCES (UNLESS SPECIFIED)	ANGULAR TOL ± 3	EC NO: 601885				
4 PLACES ±	3 PLACES ±	DRWN: NVENKATESHSH 2018/05/31	MX64 SAE RECEPTACLE TERMINAL			
2 PLACES ± 0.10	1 PLACE ± 0.3	CHK'D: JPRUNEAU 2018/08/09				
0 PLACES ±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPR: TOMSMITH 2018/08/13	PRODUCT CUSTOMER DRAWING			
THIRD ANGLE PROJECTION	DRAWING	INITIAL REVISION:				
		DRWN: DHEMNANI 2007/04/12	DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
		APPR: BMOSEY 2007/04/13	SD-33468-001	PSD	001	G3
			MATERIAL NUMBER	CUSTOMER	SHEET NUMBER	
			SEE TABLE	GENERAL MARKET	1 OF 1	

DOCUMENT STATUS	P1	RELEASE DATE	2018/08/13	12:08:30
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